

FEATURES

- Small glass structure ensures high reliability
- VBO:28-36V version
- Low breakover current
- High temperature soldering guaranteed
260°C/10 seconds,0.375"(9.5mm) lead length,
5 lbs. (2.3kg) tension

MECHANICAL DATA

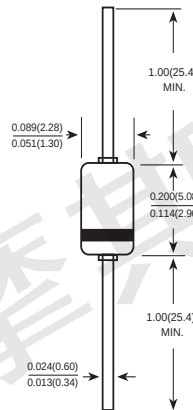
Case: JEDEC DO-35 glass body

Terminals: Plated axial leads, solderable per MIL-STD-750,
Method 2026

Mounting Position: Any

Weight:0.005 ounce, 0.14gram

DO-35(GLASS)



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Type Number	TEST CONDITION	SYMBOLS	VALUE			UNITS
			Min.	Typ.	Max.	
Breakover voltage *	C=22nF **	V_{BO}	28	32	36	VOLTS
Breakover voltage symmetry	C=22nF **	$ +V_{BO} - -V_{BO} $	-3		3	VOLTS
Dynamic breakover voltage *	(NOTE 1)	$ \Delta V \pm $	5			VOLTS
Output voltage *	DIAGRAM2	V_o	5			VOLTS
Breakover current *	C=22nF **	I_{BO}			100	μA
Rise time *	DIAGRAM3	t_r		1.5		μS
Leakage current *	$V_R = 0.5V_{BO}$	I_B			10	μA
Power dissipation on printed circuit	$T_A = 65^\circ C$	P_d			150	mW
Repetitive peak on-state current	$t_p = 20\mu s$ $f = 100Hz$	I_{TRM}			2	A
Thermal Resistances from Junction to ambient		$R_{\theta JA}$			400	$^\circ C/W$
Thermal Resistances from Junction to lead		$R_{\theta JL}$			150	$^\circ C/W$
Operating junction and storage temperature range		T_J, T_{STG}	-40		125	$^\circ C$

* :Electrical characteristic appoicaboe in forward and reverse directions.

** :Connected in parallel with the devices.

Note 1: I_{BO} from I_{BO} to 10mA

RATINGS AND CHARACTERISTIC CURVES

DIAGRAM 1:CURRENT-VOLTAGE CHARACTERISTICS

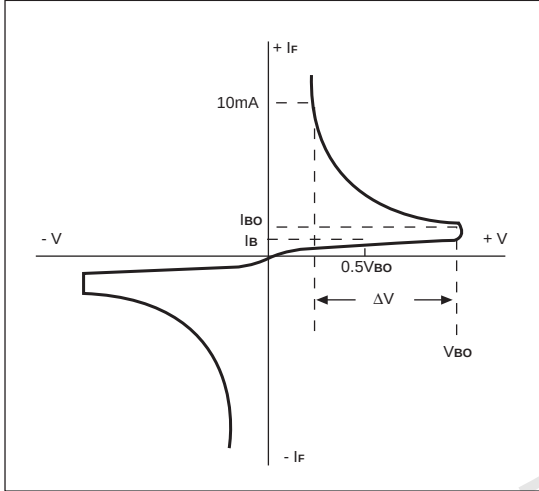


FIG. 1-POWER DISSIPATION VERSUS AMBIENT TEMPERATURE(MAXIMUM VALUES)

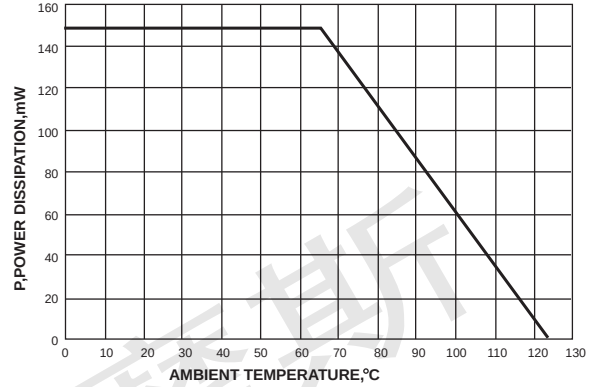


FIG. 2-PEAK PULSE CURRENT VERSUS PULSE DURATION (MAXIMUM VALUES)

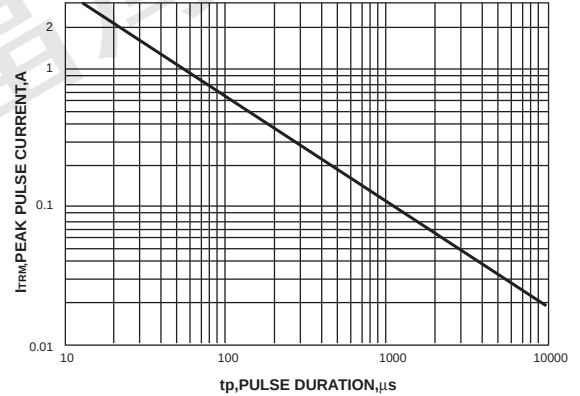


DIAGRAM 2:TEST CIRCUIT OUTPUT VOLTAGE

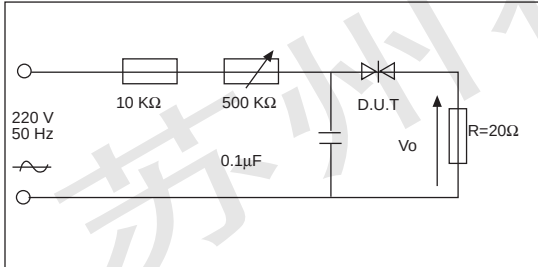


DIAGRAM 3:TEST CIRCUIT SEE DIAGRAM 2.ADJUST R FOR $I_P=0.5A$

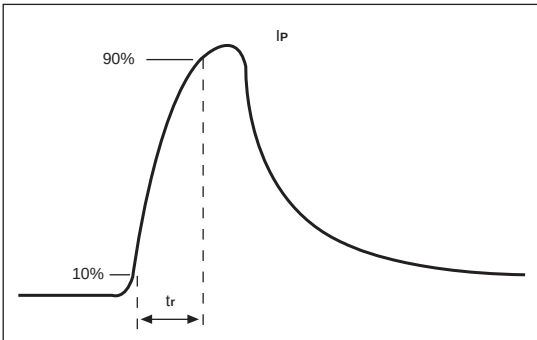


FIG. 3-RELATIVE VARIATION OF V_{BO} VERSUS JUNCTION TEMPERATURE(TYPICAL VALUES)

